

## CLAIMS

1. A plating solution which contains ionic Fe,  
ionic Pt, and a complex agent, at a molar ratio of  
5 the ionic Fe to the ionic Pt ranging from 0.75 to 3.

2. The plating solution according to claim 1,  
wherein the complex agent contains tartrate ions or  
citrate ions.

3. The plating solution according to claim 1,  
10 wherein the concentration of the ionic Fe ranges from  
0.005 mol/L to 0.1 mol/L.

4 The plating solution according to claim 1,  
wherein the plating solution has a pH ranging from  
5.0 to 10.5.

15 5. The plating solution according to claim 1,  
wherein the ionic Fe and the ionic Pt form a double  
complex constituted of an Fe complex and a Pt complex.

6. The plating solution according to claim 1,  
wherein the plating solution contains ionic Cu and a  
20 complex agent for the ionic Cu.

7. A process for producing a structure  
comprising steps of:  
providing an electrode and an object to be plated in  
a vessel containing a plating solution set forth in  
25 any of claims 1 to 6, and  
plating the object with a magnetic material  
containing FePt from the plating solution by applying

voltage to the electrode to form a structure.

8. A process for producing a structure,  
wherein the structure formed in claim 7 is heat-  
treated further at a temperature ranging from 450°C to  
5 750°C.

9. A process for producing a structure,  
wherein the structure set forth in claim 7 is heat-  
treated further in the presence of hydrogen.

10. The process for producing a structure  
10 according to claim 7, wherein the object to be plated  
is a structure having holes, and the step of plating  
the object to form the structure is deposition of the  
magnetic material containing FePt into the holes.

11. An apparatus, having a plating solution as  
15 set forth in any of claims 1 to 6, a vessel for  
holding the plating solution, and electrodes, for  
conducting plating by application of a voltage to the  
electrodes.